



STU/D608S

SamHop Microelectronics Corp.

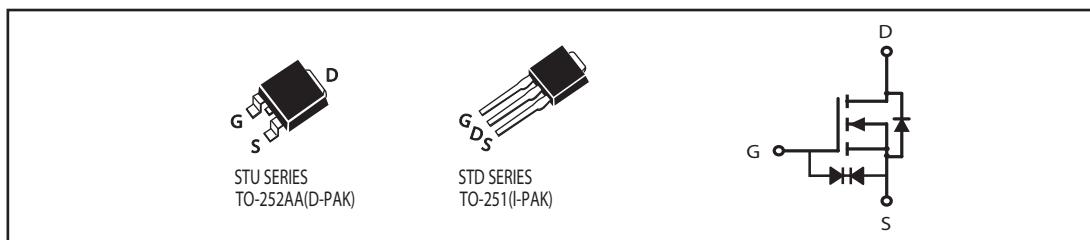
Feb. 06 2007

N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
V _{DSS}	I _D	R _{D(S)} (ON) (mΩ) Max
60V	16A	55 @ V _{G(S)} = 10V
		65 @ V _{G(S)} = 4.5V

FEATURES

- Super high dense cell design for low R_{D(S)}(ON).
- Rugged and reliable.
- TO-252 and TO-251 Package.
- ESD Protected.



ABSOLUTE MAXIMUM RATINGS (T_A=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{D(S)}	60	V
Gate-Source Voltage	V _{G(S)}	±20	V
Drain Current-Continuous ^a @ T _a	25°C	16	A
	70°C	10	A
-Pulsed ^b	I _{D(M)}	30	A
Drain-Source Diode Forward Current ^a	I _S	10	A
Maximum Power Dissipation ^a	T _a = 25°C	50	W
	T _a =70°C	35	
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 175	°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	R _{θJC}	3	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	50	°C/W

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N-Channel ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=48\text{V}, V_{\text{GS}}=0\text{V}$		1		μA
Gate-Body Leakage	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$			±10	μA
ON CHARACTERISTICS ^a						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.0	1.6	3.0	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$		46	55	m ohm
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4\text{A}$		50	65	m ohm
On-State Drain Current	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}}=5\text{V}, V_{\text{GS}}=10\text{V}$	20			A
Forward Transconductance	g_{FS}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=8\text{A}$		19		S
DYNAMIC CHARACTERISTICS ^b						
Input Capacitance	C_{iss}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$ $f=1.0\text{MHz}$		620		pF
Output Capacitance	C_{oss}			71		pF
Reverse Transfer Capacitance	C_{rss}			45		pF
SWITCHING CHARACTERISTICS ^b						
Turn-On Delay Time	$t_{\text{D}(\text{ON})}$	$V_{\text{DD}}=30\text{V}$ $I_{\text{D}}=8\text{A}$ $V_{\text{GS}}=10\text{V}$ $R_{\text{GEN}}=3.3\text{ ohm}$		9.5		ns
Rise Time	t			12.5		ns
Turn-Off Delay Time	$t_{\text{D}(\text{OFF})}$			42		ns
Fall Time	t			9		ns
Total Gate Charge	Q_{g}	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=8\text{A}, V_{\text{GS}}=10\text{V}$		13		nC
		$V_{\text{DS}}=30\text{V}, I_{\text{D}}=8\text{A}, V_{\text{GS}}=4.5\text{V}$		6.4		nC
Gate-Source Charge	Q_{gs}	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=8\text{A}$ $V_{\text{GS}}=10\text{V}$		1.4		nC
Gate-Drain Charge	Q_{gd}			3.2		nC

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ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS ^a						
Diode Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 10A$		0.9	1.3	V

Notes

- a.Pulse Test:Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- b.Guaranteed by design, not subject to production testing.

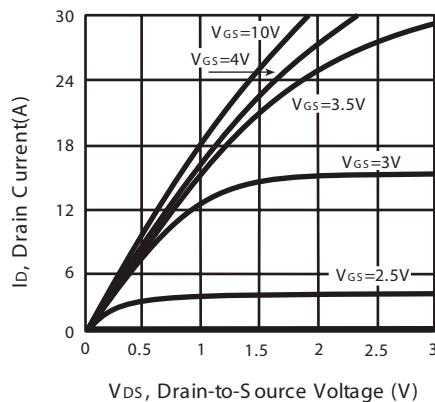


Figure 1. Output Characteristics

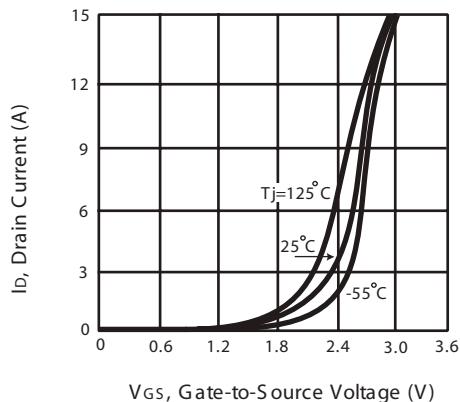


Figure 2. Transfer Characteristics

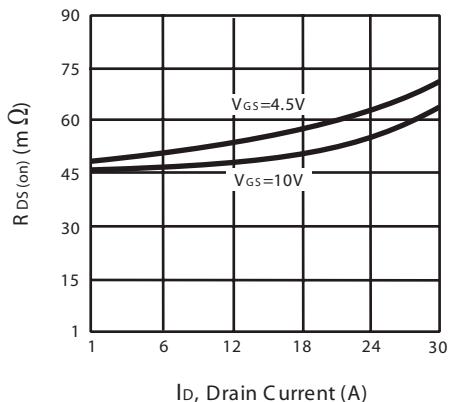


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

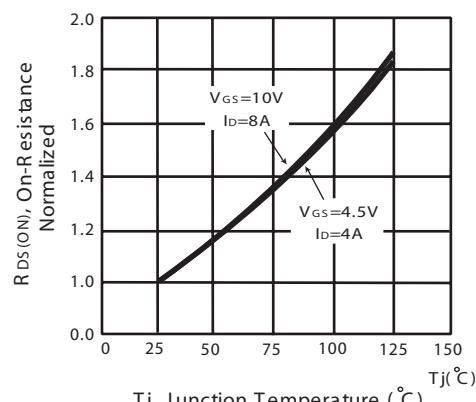


Figure 4. On-Resistance Variation with Drain Current and Temperature

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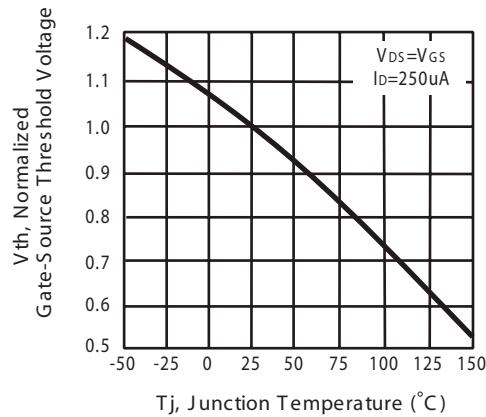


Figure 5. Gate Threshold Variation with Temperature

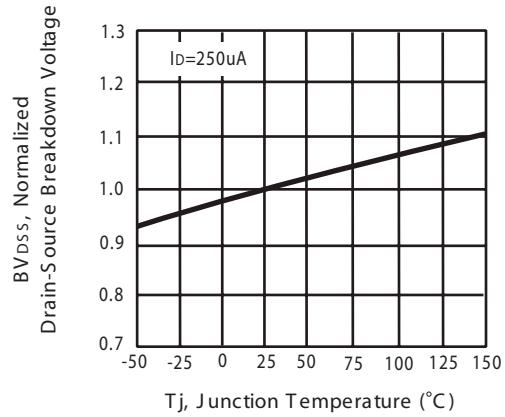


Figure 6. Breakdown Voltage Variation with Temperature

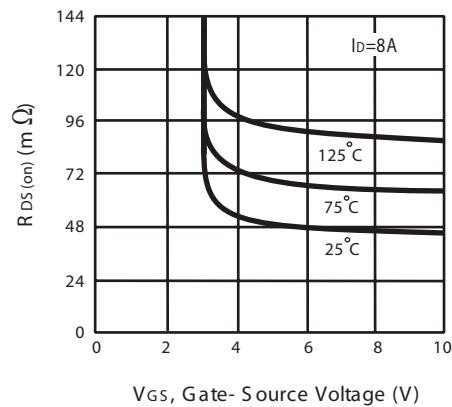


Figure 7. On-Resistance vs. Gate-Source Voltage

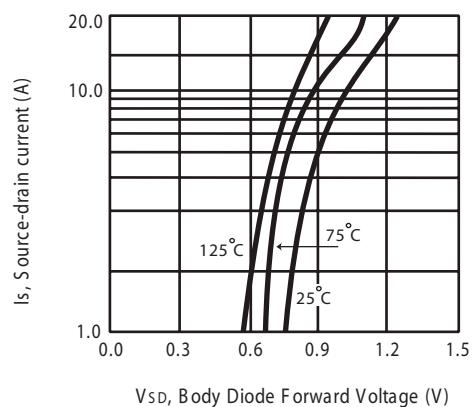


Figure 8. Body Diode Forward Voltage Variation with Source Current

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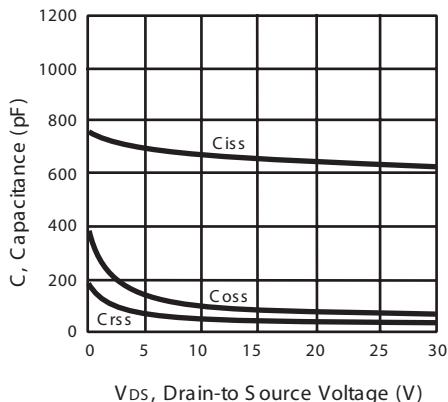


Figure 9. Capacitance

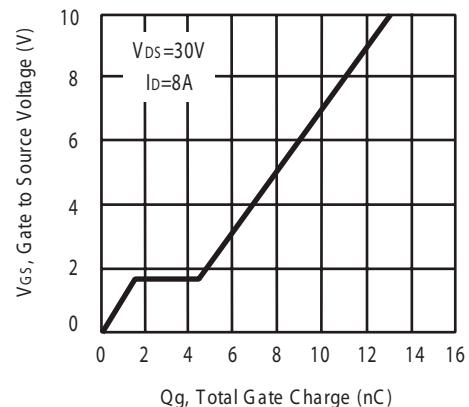


Figure 10. Gate Charge

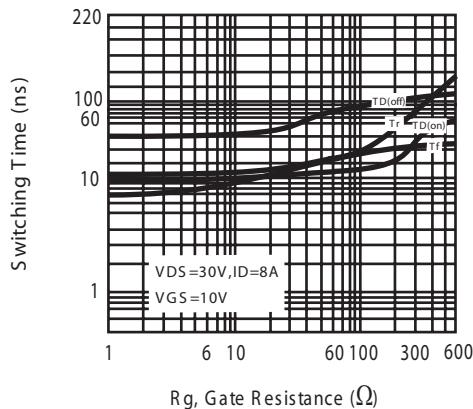


Figure 11. switching characteristics

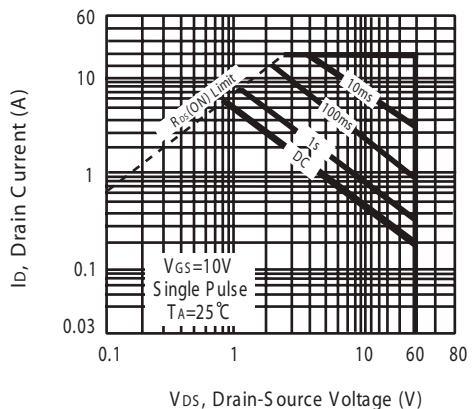


Figure 12. Maximum Safe Operating Area

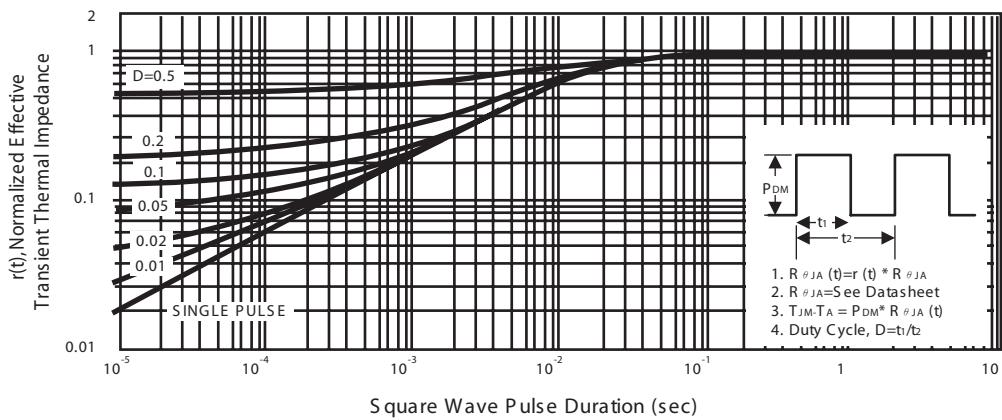


Figure 13. Normalized Thermal Transient Impedance Curve

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PACKAGE OUTLINE DIMENSIONS

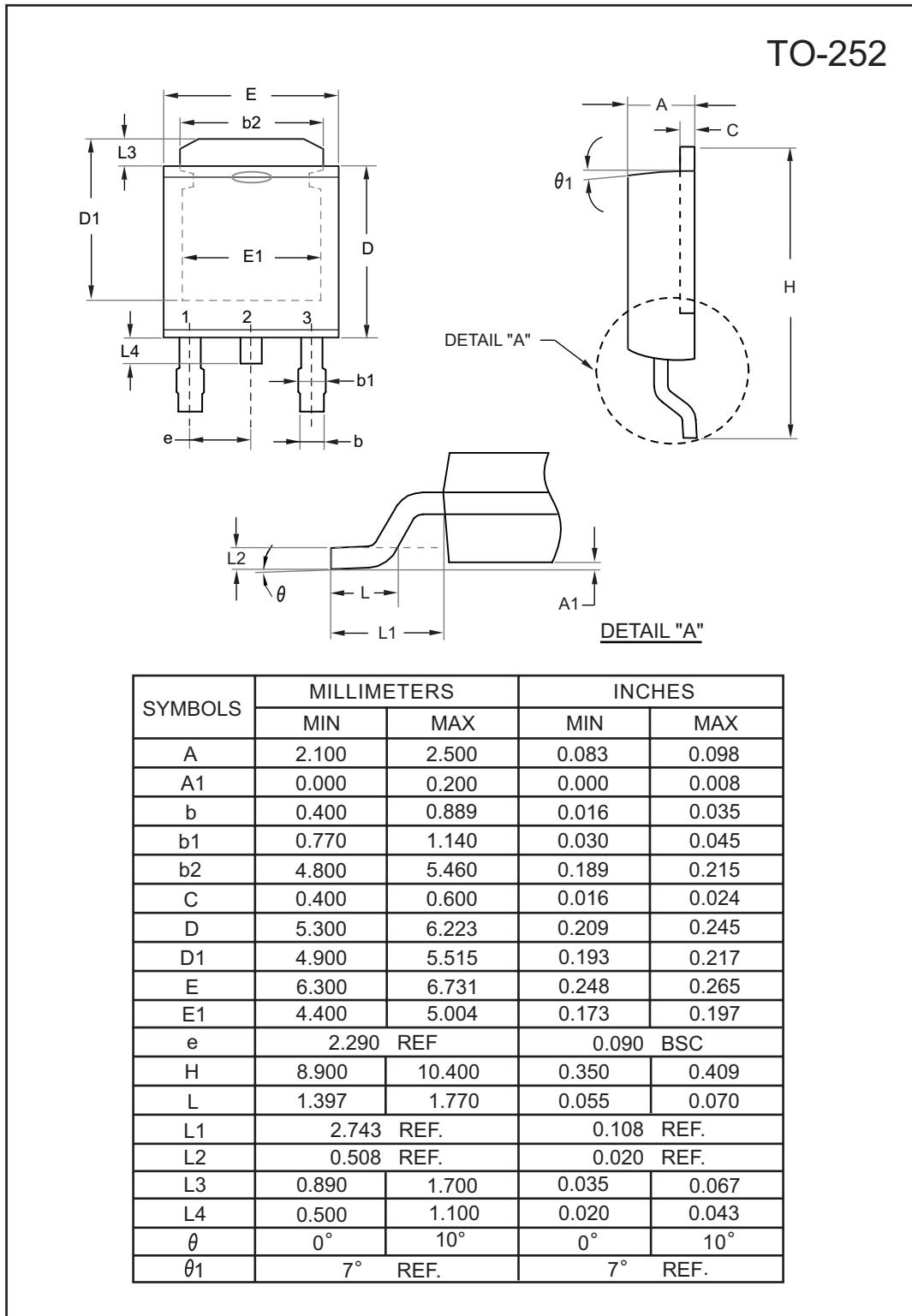
TO-251

The technical drawing illustrates the TO-251 package with two views: a top view showing the lead frame and a side view showing the profile. Key dimensions labeled include:
 - Top View: D1, H, E, E1, E2, L, D2, D, P, B, B1, B2, L1, L2.
 - Side View: A, C, A1, D3.

SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.100	2.500	0.083	0.098
A1	0.350	0.650	0.014	0.026
B	0.400	0.800	0.016	0.031
B1	0.650	1.050	0.026	0.041
B2	0.500	0.900	0.020	0.035
C	0.400	0.600	0.016	0.024
D	5.300	5.700	0.209	0.224
D1	4.900	5.300	0.193	0.209
D2	6.700	7.300	0.264	0.287
D3	7.000	8.000	0.276	0.315
H	13.700	15.300	0.539	0.602
E	6.300	6.700	0.248	0.264
E1	4.600	4.900	0.181	0.193
E2	4.800	5.200	0.189	0.205
L	1.300	1.700	0.051	0.067
L1	1.400	1.800	0.055	0.071
L2	0.500	0.900	0.020	0.035
P	2.300 BSC		0.091 BSC	

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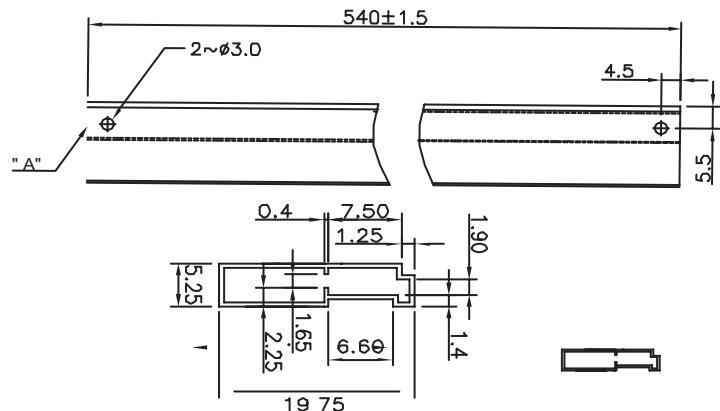
PACKAGE OUTLINE DIMENSIONS



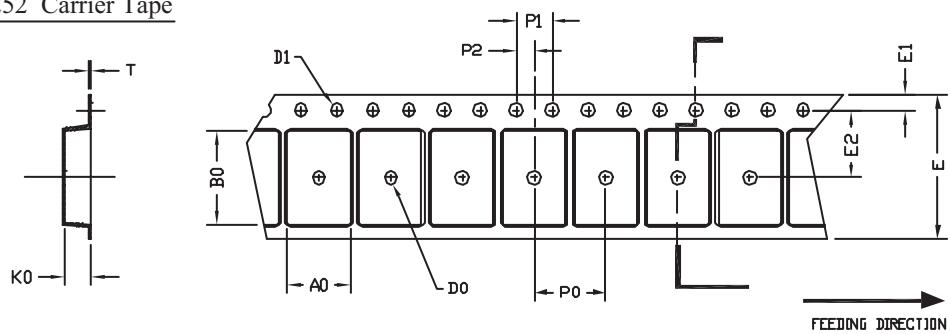
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TO251 Tube/TO-252 Tape and Reel Data

TO-251 Tube



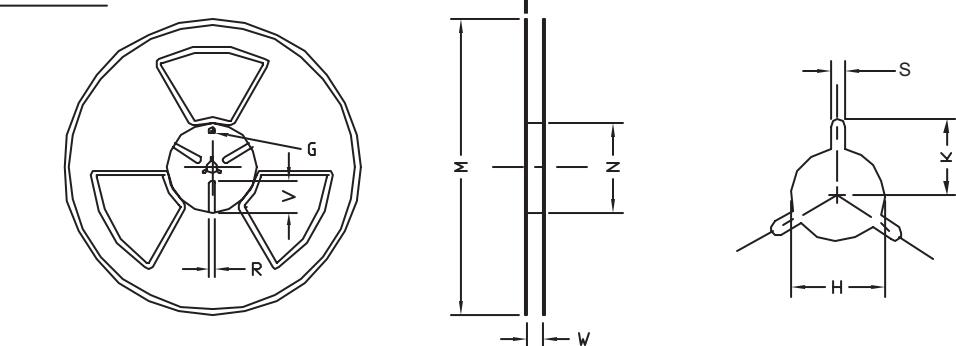
TO-252 Carrier Tape



UNIT:mm

PACKAGE	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T	
TO-252 (16 mm)	6.80 ±0.1	10.3 ±0.1	2.50 ±0.1	ψ 2	ψ 1.5 + 0.1 - 0	16.0	0.3±	0.1±	7.5 ±0.15	8.0 ±0.1	4.0 ±0.1	2.0 ±0.15	0.3 ±0.05

TO-252 Reel



UNIT:mm

TAPE SIZE	REEL SIZE	M	N	W	T	H	K	S	G	R	V
16 mm	ψ 330	ψ 330 ± 0.5	ψ 97 ± 1.0	17.0 + 1.5 - 0	2.2	ψ 13.0 + 0.5 - 0.2	10.6	2.0 ± 0.5	---	---	---